



THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	UNIT		
Junction-to-ambient thermal resistance	R _{OJA}	70	°C/W		

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
40	HS1A HS1B HS1D HS1F	I _F = 1A, T _J = 25°C	V _F	-	1.0	V
Forward voltage ⁽¹⁾	HS1G			-	1.3	V
	HS1J HS1K HS1M			-	1.7	V
		T _J = 25°C	I _R	-	5	μA
Reverse current @ rated V _R ⁽²⁾		T _J = 100°C		-	50	μΑ
		T _J = 125°C		-	150	μΑ
Junction capacitance	HS1A HS1B HS1D HS1F HS1G	1MHz, V _R = 4.0V	С	20	-	pF
	HS1J HS1K HS1M			15	-	pF
Reverse recovery time	HS1A HS1B HS1D HS1F HS1G	I _F = 0.5A, I _R = 1.0A, I _{rr} = 0.25A	t _{rr}	-	50	ns
	HS1J HS1K HS1M			-	75	ns

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING		
HS1x	DO-214AC (SMA)	7,500 / Tape & Reel		

Notes:

1. "x" defines voltage from 50V(HS1A) to 1000V(HS1M)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

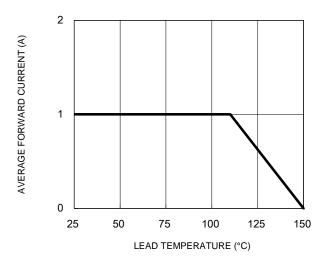


Fig.3 Typical Reverse Characteristics

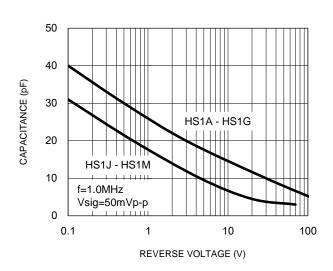
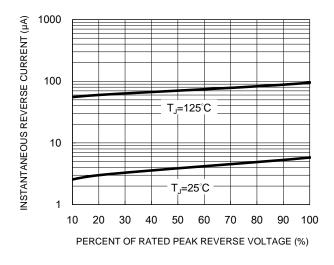


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



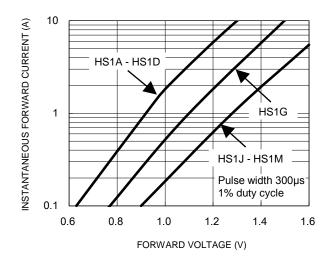
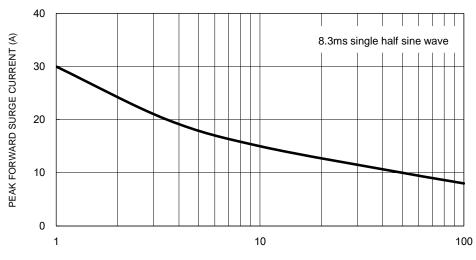


Fig.5 Maximum Non-Repetitive Forward Surge Current



NUMBER OF CYCLES AT $60\ Hz$

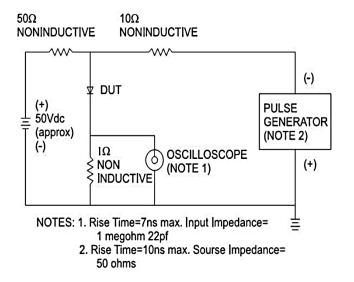


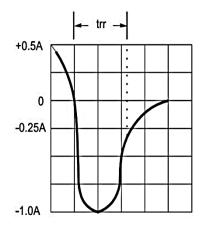


CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.6 Reverse Recovery Time Characteristic and Test Circuit Diagram



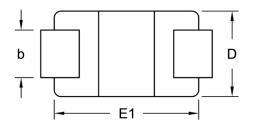


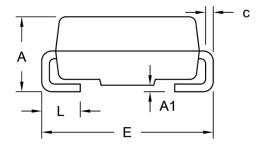




PACKAGE OUTLINE DIMENSIONS

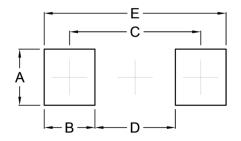
DO-214AC (SMA)





DIM.	Unit (mm)		Unit (inch)		
Dilvi.	Min.	Max.	Min.	Max.	
Α	1.99	2.50	0.078	0.098	
A1	0.10	0.20	0.004	0.008	
b	1.27	1.58	0.050	0.062	
С	0.15	0.31	0.006	0.012	
D	2.29	2.83	0.090	0.111	
E	4.95	5.33	0.195	0.210	
E1	4.06	4.60	0.160	0.181	
L	0.90	1.41	0.035	0.056	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	1.68	0.066
В	1.52	0.060
С	3.93	0.155
D	2.41	0.095
E	5.45	0.215

MARKING DIAGRAM



= Marking Code P/N G = Green Compound

= Date Code ΥW F = Factory Code



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